

L Number	Hits	Search Text	DB	Time stamp
-	1	(electrolytic near4 plating) and (feeder adj film)	USPAT; US-PGPUB	2002/11/26 18:05
-	3227	(electrolytic near4 plating) and substrate	USPAT; US-PGPUB	2002/11/22 11:07
-	4669	electrolytic near4 plating	USPAT; US-PGPUB	2002/11/22 13:52
-	3142	electrolytic adj plating	USPAT; US-PGPUB	2002/11/22 13:52
-	3142	electrolytic adj plating	USPAT; US-PGPUB	2002/11/22 13:52
-	2452	(electrolytic adj plating) and (substrate or semiconductor)	USPAT; US-PGPUB	2002/11/22 13:53
-	37	tonami.in.	USPAT; US-PGPUB	2002/11/22 14:06
-	3	tonami.in. and Yoshiyuki	USPAT; US-PGPUB	2002/11/22 14:06
-	37	tonami.in.	USPAT; US-PGPUB	2002/11/22 14:06
-	485	tonami.in.	JPO; DERWENT	2002/11/22 14:06
-	0	tonami.in. and yoshiyuki	JPO; DERWENT	2002/11/22 14:07
-	34	tonami.in. and yoshiyuki	JPO; DERWENT	2002/11/22 14:13
-	2143	216/13.ccls. or 216/18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:15
-	23	(216/13.ccls. or 216/18.ccls.) and 216/40.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:15
-	1	((216/13.ccls. or 216/18.ccls.) and 216/40.ccls.) and 216/100.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:16
-	147	(216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:16
-	0	((216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.) and 216/40.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:16
-	11	((216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.) and 216/100.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:18
-	1278	205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:19
-	35	(205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.) and taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 14:19
-	1	((205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.) and taper\$4) and lift-off	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/22 15:37

-	118	205/80.ccls.	USPAT; US-PGPUB	2002/11/22 15:09
-	121	205/169.ccls.	USPAT; US-PGPUB	2002/11/22 15:10
-	0	(205/80, 123, 157, "169" and "223").ccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:40
-	0	(205/80,123,157,169,223).ccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:41
-	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
-	0	c25d05/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
-	18607	c25d005/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
-	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
-	651	c25d005/\$.ipc. and (electrolytic near4 plating)	JPO; DERWENT	2002/11/22 18:46
-	55	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base) and (cu or copper or ti or titanium)	JPO; DERWENT	2002/11/22 16:51
-	285	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4)	JPO; DERWENT	2002/11/22 17:38
-	28	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	JPO; DERWENT	2002/11/22 18:41
-	3874	(205/\$ or 216/\$).ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:20
-	1492	205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:24
-	1410	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:23
-	1297	205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)	USPAT; US-PGPUB	2002/11/22 18:28
-	149	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$8)	USPAT; US-PGPUB	2002/11/22 18:32
-	148	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$6)	USPAT; US-PGPUB	2002/11/22 18:32
-	168	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wir\$4 near7 form\$5)	USPAT; US-PGPUB	2002/11/22 18:34
-	43	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and ((wire or wiring) near7 (formation or pattern or fabrication))	USPAT; US-PGPUB	2002/11/27 09:52
-	1312	(205/80,123,125,223,157).ccls.	USPAT; US-PGPUB	2002/11/22 18:40
-	1868	(216/13,18,40,100).ccls.	USPAT; US-PGPUB	2002/11/22 18:41
-	3103	((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)	USPAT; US-PGPUB	2002/11/22 18:41
-	1015	((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)	USPAT; US-PGPUB	2002/11/22 18:43
-	964	((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:44

-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 15:04
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 11:59
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:55
-	1	4866008.pn.	USPAT; US-PGPUB	2002/11/23 17:09
-	103	205/186.ccls.	USPAT; US-PGPUB	2002/11/27 09:45
-	361	(((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/26 18:54
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:59
-	263	(((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)) not ((((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating))	USPAT; US-PGPUB	2002/11/26 18:56
-	270	(205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117 and ((electrolytic near4 plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 10:42
-	19	205/186.ccls. and ((feed\$4 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (partial\$4 or mask or pattern))	USPAT; US-PGPUB	2002/11/27 10:34
-	3	"2000008247"	JPO; DERWENT	2002/11/27 10:41
-	22685	h011021/3205.ipc.	JPO; DERWENT	2002/11/27 10:41
-	47	h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near4 plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:48
-	1	04262536.pn.	DERWENT	2002/11/27 14:29
-	1	"04262536"	DERWENT	2002/11/27 14:30
-	2	"04262536"	JPO; DERWENT	2002/11/27 15:10
-	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 15:10

-	0	(205/186,123,125,223,157). and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:51
-	283	(205/186,123,125,223,157).cccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:56
-	384	(h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:55
-	337	((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4))	JPO; DERWENT	2002/11/27 15:53
-	28	((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) and ((remove or etch) near7 (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed))	JPO; DERWENT	2002/11/27 16:18
-	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 16:18